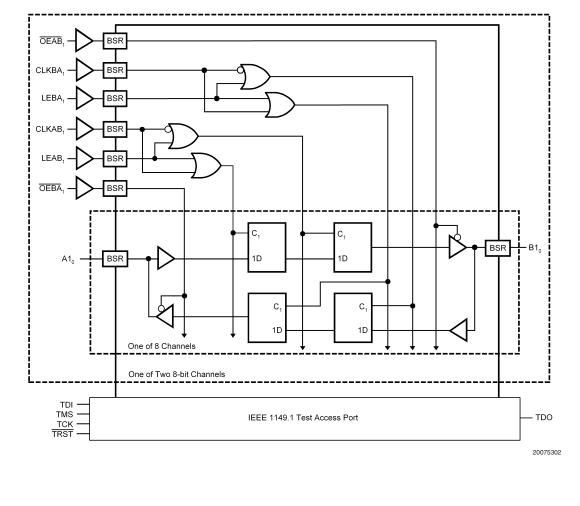


#### **SCAN16512A** Low Voltage Universal 16-bit IEEE 1149.1 Bus **Transceiver with TRI-STATE Outputs General Description Features**

The SCAN16512A is a high speed, low-power universal bus transceiver featuring data inputs organized into two 8-bit bytes with output enable and latch enable control signals. This function is configurable as a D-type Latch or Flip-Flop. and can operate in transparent, latched, or clocked mode. This device is compliant with IEEE 1149.1 Standard Test Access Port and Boundary Scan Architecture with the incorporation of the defined boundary-scan test logic and test access port consisting of Test Data Input (TDI), Test Data Out (TDO), Test Mode Select (TMS), Test Clock (TCK), and Test Reset (TRST).

- IEEE 1149.1 (JTAG) Compliant
- 2.7V to 3.6V V<sub>CC</sub> Operation
- TRI-STATE outputs for bus-oriented applications
- Dual byte-wide data for bus applications
- Power down high Impedance inputs and outputs
- Optional Bus Hold on data inputs eliminates the need for external pullup/pulldown resistors (SCANH16512A, SCANH162512A versions)
- Optional 25Ω series resistors in outputs to minimize noise and eliminate termination resistors (SCAN162512A, SCANH162512A versions)
- Supports live insertion/withdrawal
- Includes CLAMP and HIGHZ instructions





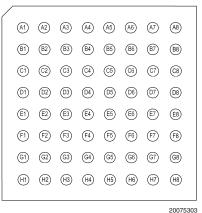
SCAN16512A

Pin	Description
Name	
A1 <sub>0</sub> -A1 <sub>7</sub> ,	Normal-function A-bus I/O ports. See function table for normal-mode logic.
A2 <sub>0</sub> -A2 <sub>7</sub>	
В1 <sub>0</sub> -В1 <sub>7</sub> ,	Normal-function B-bus I/O ports. See function table for normal-mode logic.
B2 <sub>0</sub> -B2 <sub>7</sub>	
CLKAB <sub>1</sub> ,	Normal-function clock inputs.See function table for normal-mode logic.
CLKBA <sub>1</sub> ,	
CLKAB <sub>2</sub> ,	
CLKBA <sub>2</sub>	
GND	Ground
V <sub>cc</sub>	Supply Voltage
LEAB <sub>1</sub> ,	Normal-function latch enables. See function table for normal-mode logic.
LEBA <sub>1</sub> ,	
LEAB <sub>2</sub> ,	
$\overline{OEAB}_1,$ $\overline{OEBA}_1,$	Normal-function output enables. See function table for normal-mode logic.
$\overline{OEBA}_{2}$ ,	
$\overline{OEBA}_2$	
TDO	The Test Data Output to support IEEE Std 1149.1-1990. TDO is the serial output for shifting data through
	the instruction register or selected data register.
TMS	The Test Mode Select input to support IEEE Std 1149.1-1990. TMS directs the device through it's TAP
	controller states. An internal pull-up forces TMS high if left unconnected.
тск	The Test Clock input to support IEEE Std 1149.1-1990. Test operations of the device are synchronous to
	TCK. Data is captured on the rising edge of TCK and outputs change on the falling edge of TCK.
TDI	The Test Data Input to support IEEE Std 1149.1-1990. TDI is the serial input to shift data through the
	instruction register or the selected data register. An internal pull-up resistor forces TDI high if left
	unconnected.
TRST	The Test Reset Input to support IEEE Std 1149.1-1990. TRST is the asynchronous reset pin which will
	force the TAP controller to it's initialization state when active. An internal pullup resistor forces TRST high

## **BGA** Pinout

	1	2	3	4	5	6	7	8
Α	A1 <sub>0</sub>	A1 <sub>2</sub>	A1 <sub>4</sub>	A1 <sub>6</sub>	A2 <sub>0</sub>	A2 <sub>2</sub>	A2 <sub>4</sub>	A2 <sub>6</sub>
В	A1 <sub>1</sub>	A1 <sub>3</sub>	A1 <sub>5</sub>	A1 <sub>7</sub>	A2 <sub>1</sub>	A2 <sub>3</sub>	A2 <sub>5</sub>	A2 <sub>7</sub>
С	TRST	CLKAB <sub>1</sub>	LEAB <sub>1</sub>	OEAB <sub>1</sub>	GND	CLKAB <sub>2</sub>	LEAB <sub>2</sub>	OEAB <sub>2</sub>
D	TMS	GND	V <sub>cc</sub>	GND	V <sub>CC</sub>	GND	TDI	TDO
E	ТСК	GND	V <sub>cc</sub>	V <sub>CC</sub>	GND	GND	N/C	V <sub>cc</sub>
F	CLKBA <sub>1</sub>	LEBA <sub>1</sub>	OEBA <sub>1</sub>	GND	N/C	CLKBA <sub>2</sub>	LEBA <sub>2</sub>	OEBA <sub>2</sub>
G	B1 <sub>1</sub>	B1 <sub>3</sub>	B1 <sub>5</sub>	B1 <sub>7</sub>	B2 <sub>1</sub>	B2 <sub>3</sub>	B2 <sub>5</sub>	B2 <sub>7</sub>
н	B1 <sub>o</sub>	B1 <sub>2</sub>	B1 <sub>4</sub>	B1 <sub>6</sub>	B2 <sub>0</sub>	B2 <sub>2</sub>	B2 <sub>4</sub>	B2 <sub>6</sub>

#### **Connection Diagram**



Top View See NS Package Number SLC64A

#### **Truth Table**

#### Function Table (Note 1)

	Inp		Outputs	
OEAB	LEAB	CLKAB	Α	В
L	L	L	Х	B <sub>o</sub> (Note 2)
L	L	1	L	L
L	L	↑	Н	н
L	Н	Х	L	L
L	Н	Х	Н	н
н	Х	Х	Х	Z
H - HIGH Volta				

H = HIGH Voltage Level L = LOW Voltage Level

X = Immaterial (HIGH or LOW, inputs may not float)

Z = High Impedance

Note 1: A-to-B data flow is shown. B-to-A data flow is similar, but uses  $\overline{\text{OEBA}}$ , LEBA, and CLKBA.

Note 2: Output level before the indicated steady-state input conditions were established.

#### **Functional Description**

In the normal mode, these devices are 16-bit universal bus transceivers that combine D-type latches and D-type flipflops to allow data flow in transparent, latched, or clocked modes. They can be used as two 8-bit transceivers, or as one 16-bit transceiver. The test circuitry can be activated by the TAP to take snapshot samples of the data appearing at the device pins or to perform a self test on the boundary-test cells. Activating the TAP may affect the normal functional operation of the universal bus transceivers. When the TAP is activated, the test circuitry performs boundary-scan test operations according to the protocol described in IEEE Std 1149.1-1990.

Data flow in each direction is controlled by output-enable  $(\overline{OEAB} \text{ and } \overline{OEBA})$ , latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the

devices operate in the transparent mode when LEAB is high. When LEAB is low, the A data is latched while CLKAB is held at a static low or high logic level. Otherwise, if LEAB is low, A data is stored on a low-to-high transition of CLKAB. When OEAB is LOW, the B outputs are active. When OEAB is HIGH, the B outputs are in the high-impedance state. B-to-A data flow is similar to A-to-B data flow but uses the OEBA, LEBA, and CLKBA inputs.

Five dedicated test pins are used to observe and control the operation of the test circuitry: test data input (TDI), test data output (TDO), test mode select (TMS), test clock (TCK), and test reset (TRST). All testing and scan operations are synchronized to the TAP interface.

For details about the sequence of boundary scan cells in the SCAN16512A, please refer to the BSDL (Boundary Scan Description Language) file available on our website.

# SCAN16512A

#### Absolute Maximum Ratings (Note 3)

	-
Supply Voltage (V <sub>CC</sub> )	-0.5V to +4.6V
DC Input Diode Current (IIK)	
$V_1 = -0.5V$	–50 mA
DC Output Diode Current (I <sub>OK</sub> )	
$V_{\rm O} = -0.5 V$	–50 mA
DC Input Voltage (V <sub>I</sub> )	-0.5V to 4.6V
DC Output Voltage (V <sub>O</sub> )	-0.5V to 4.6V
DC Output Source/Sink Current (I <sub>O</sub> )	±50 mA
DC V <sub>CC</sub> or Ground Current	
Per Supply Pin	±100 mA
Junction Temperature	+150°C
Storage Temperature	–65°C to +150°C
Lead Temperature (Solder, 4sec)	
64L BGA	220 °C
Thermal Resistance	
BGA $\theta_{JA}$	62°C/W

Package Derating	16.1mW/°C above
	25°C
ESD (Min)	2000V

## Recommended Operating Conditions

Supply Voltage (V <sub>CC</sub> )	
SCAN16512A	2.7V to 3.6V
Input Voltage (V <sub>I</sub> )	0V to 3.6V
Output Voltage (V <sub>O</sub> )	0V to 3.6V
Operating Temperature (T <sub>A</sub> )	
Industrial	–40°C to +85°C

**Note 3:** Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. National does not recommend operation of SCAN circuits outside databook specifications.

## **DC Electrical Characteristics**

Symbol	Parameter	V <sub>cc</sub>	Industrial		Units	Conditions
		(V)	$T_A = -40^{\circ}$	C to +85°C		
			Min	Max		
V <sub>IH</sub>	Minimum High Input Voltage	2.7	2.0		V	V <sub>OUT</sub> = 0.1V
		3.6	2.0			or V <sub>CC</sub> -0.1
V <sub>IL</sub>	Maximum Low Input Voltage	2.7		0.8	V	$V_{OUT} = 0.1V$
		3.6		0.8		or V <sub>CC</sub> -0.1
V <sub>он</sub>	Minimum High Output Voltage	2.7	2.5		V	I <sub>OUT</sub> = -100
	All Outputs, All Options	3.6	3.4			μA
	Minimum High Output Voltage	2.7	2.2		V	$V_{IN} = V_{IL}$ or
	TDO Outputs, All Options					V <sub>IH</sub> ,
						$I_{OH} = -12m/$
		3.0	2.2		V	$V_{IN} = V_{IL}$ or
						V <sub>IH</sub>
		ļ				$I_{OH} = -24m/$
	Minimum High Output Voltage	2.7	2.2		V	$V_{IN} = V_{IL}$ or
	A and B Ports: SCAN16512A					V <sub>IH</sub>
	and SCANH16512A options					$I_{OH} = -12mA$
		3.0	2.2		V	$V_{IN} = V_{IL}$ or
						$V_{IH}$ $I_{OH} = -24mA$
	Minimum High Output Voltage	2.7	2.2		V	$V_{\rm IN} = V_{\rm IL}$ or
	A and B Ports: SCAN162512A	2.7	2.2		v	
	and SCANH162512A options					$I_{OH} = -4mA$
	(25 $\Omega$ series resistor options)	3.0	2.2		V	$V_{IN} = V_{IL}$ or
						V <sub>IH</sub>
						I <sub>OH</sub> = -12mA
V <sub>OL</sub>	Maximum Low Output Voltage	2.7		0.2	V	I <sub>OUT</sub> = 100
	All Outputs, All Options					μA
		3.6		0.2		

Symbol	Parameter	V <sub>cc</sub>	Indu	strial	Units	Conditions
		(V)	T <sub>A</sub> = −40°C to +85°C			
			Min	Max		
	Maximum Low Output Voltage TDO Outputs, All Options	2.7		0.4	V	$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OL} = 12mA$
		3.0		0.55	V	$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OL} = 24mA$
	Maximum Low Output Voltage A and B Ports: SCAN16512A and SCANH16512A Options	2.7		0.4	V	$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OL} = 12mA$
		3.0		0.55	V	$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OL} = 24mA$
	Maximum Low Output Voltage A and B Ports: SCAN162512A and SCANH162512A Options	2.7		0.4	V	$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OL} = 4mA$
	(25 $\Omega$ series resistor options)	3.0		0.6	V	$V_{IN} = V_{IL}$ or $V_{IH}$ , $I_{OL} = 12mA$
I <sub>IN</sub>	Maximum Input Leakage Current	3.6		±5.0	μΑ	$V_1 = V_{CC},$ GND
I <sub>ILR</sub>	Input Low Current	3.6	-20	-250	μΑ	V <sub>IN</sub> = GND
I <sub>OZ</sub>	Maximum I/O Leakage Current	3.6		±10.0	μΑ	$V_{I} (OE) =$ $V_{IL}, V_{IH}$ $V_{I} = V_{CC},$ GND
						V <sub>O</sub> = V <sub>CC</sub> , GND
I <sub>I(HOLD)</sub>	Bus Hold Input Minimum Drive Hold Current (Note 4)	2.7	±35		μA	V <sub>I</sub> = 0.8V or 2.0V
		3.6		±500		$V_1 = 0$ to 3.6V
V <sub>IKL</sub>	Input Clamp Diode Voltage	2.7		-1.5	V	I <sub>IN</sub> = -18mA
I <sub>OFF</sub>	Power-off Leakage Current	0.0		±10.0	μΑ	V <sub>O</sub> = V <sub>CC</sub> , GND
I <sub>CC</sub>	Maximum Quiescent Supply Current	3.6		20	μΑ	
I <sub>CCt</sub>	Maximum I <sub>CC</sub> Per Input	3.6		0.5	mA	$V_1 = V_{CC} - 0.6V$

Note 4: Applies to devices with Bus Hold feature only.

SCAN16512A

**Noise Specifications** Applies to SCAN16512A and SCANH16512A options,  $C_L = 30pF$ ,  $R_L = 500\Omega$  to GND

Symbol	Parameter	V <sub>cc</sub> (V)		Units
		(•)	T <sub>A</sub> = 25°C Typical Limits	
V <sub>OLP</sub>	Quiet Output Maximum Dynamic VOL (Note 5)	3.3	1.2	V
V <sub>OLV</sub>	Quiet Output Minimum Dynamic VOL (Note 5)	3.3	-1.5	V
V <sub>OHP</sub>	Quiet Output Maximum Dynamic VOH (Note 6)	3.3	VOH + 0.9	V
V <sub>OHV</sub>	Quiet Output Minimum Dynamic VOH (Note 6)	3.3	VOH - 1.5	V

Noise Specifications Applies to SCAN162512A and SCANH162512A options, C\_L = 30pF, R\_L = 500\Omega to GND

Symbol	Parameter	V <sub>cc</sub>	Industrial	Units
		(V)	T <sub>A</sub> = 25°C	
			Typical Limits	
V <sub>OLP</sub>	Quiet Output Maximum Dynamic VOL (Note 5)	3.3	0.5	V
V <sub>OLV</sub>	Quiet Output Minimum Dynamic VOL (Note 5)	3.3	-0.4	V
V <sub>OHP</sub>	Quiet Output Maximum Dynamic VOH(Note 6)	3.3	VOH + 0.5	V
V <sub>OHV</sub>	Quiet Output Minimum Dynamic VOH (Note 6)	3.3	VOH - 0.5	V

Note 5: Maximum number of outputs is defined as n. (n-1) outputs are switched LOW while the quiet output is monitored in a LOW (VOL) state. Also, (n-1) outputs are switched HIGH while the quiet output is monitored in a LOW (VOL) state.

Note 6: Maximum number of outputs is defined as n. (n-1) outputs are switched LOW while the quiet output is monitored in a HIGH (VOH) state. Also, (n-1) outputs are switched HIGH while the quiet output is monitored in a HIGH (VOH) state.

Symbol	Parameter	SCAN16512A,	SCANH16512A	Units
		$T_{A} = -40^{\circ}$	C to +85°C	
		C <sub>L</sub> =		
		$R_L = 500\Omega$ to GND	Ω to GND	
		Min	Max	
PLH,	Propagation Delay		5.5	ns
PHL	A to B, B to A		5.5	
PLH,	Propagation Delay		6.0	ns
PHL	CLKAB to B, CLKBA to A		6.0	
PLH,	Propagation Delay		6.0	ns
PHL	LEAB to B, LEBA to A		6.0	
PLZ,	Disable Time, OEAB to B, OEBA to A		7.5	ns
PHZ			7.5	

### **AC Electrical Characteristics**

Normal Operation, over recommended operating supply voltage and temperature ranges unless otherwise specified.

Symbol	Parameter	SCAN1	62512A	Units
		$T_A = -40^\circ$	C to +85°C	
		$C_L = 30 \text{ pF}$ $R_L = 500\Omega \text{ to GND}$		
		Min	Max	
t <sub>PLH</sub> ,	Propagation Delay		6.0	ns
t <sub>PHL</sub>	A to B, B to A		6.0	
t <sub>PLH</sub> ,	Propagation Delay		6.5	ns
t <sub>PHL</sub>	CLKAB to B, CLKBA to A		6.5	
t <sub>PLH</sub> ,	Propagation Delay		6.5	ns
t <sub>PHL</sub>	LEAB to B, LEBA to A		6.5	
t <sub>PLZ</sub> ,	Disable Time, OEAB to B, OEBA to A		8.0	ns
t <sub>PHZ</sub>			8.0	
t <sub>PZL</sub> ,	Enable Time, OEAB to B, OEBA to A		8.0	ns
t <sub>PZH</sub>			8.0	

SCAN16512A

#### **AC Electrical Characteristics**

Normal Operation, over recommended operating supply voltage and temperature ranges unless otherwise specified.

Symbol	Parameter	SCANH162512A $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ $C_L = 30 \text{ pF}$ $R_L = 500\Omega \text{ to GND}$		Units					
					Min	Мах	7		
					t <sub>PLH</sub> ,	Propagation Delay		6.0	ns
					t <sub>PHL</sub>	A to B, B to A		6.0	
		t <sub>PLH</sub> ,	Propagation Delay		6.5	ns			
t <sub>PHL</sub>	CLKAB to B, CLKBA to A		6.5						
t <sub>PLH</sub> ,	Propagation Delay		6.5	ns					
t <sub>PHL</sub>	LEAB to B, LEBA to A		6.5						
t <sub>PLZ</sub> ,	Disable Time, OEAB to B, OEBA to A		8.0	ns					
t <sub>PHZ</sub>			8.0						
t <sub>PZL</sub> ,	Enable Time, OEAB to B, OEBA to A		8.0	ns					
t <sub>PZH</sub>			8.0						

#### **AC Operating Requirements**

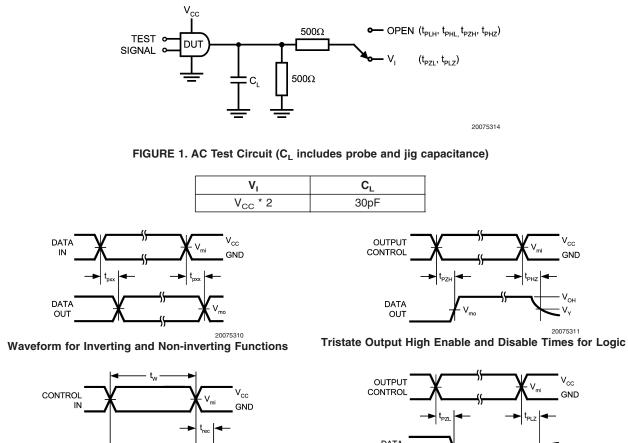
Normal Operation, over recommended operating supply voltage and temperature ranges unless otherwise specified

Symbol	Parameter	All Options	Units	
	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			
		$C_{L} = 30 \text{ pF},$		
		$R_L = 500\Omega$ to GND		
		Guaranteed Minimum	]	
t <sub>s</sub>	Setup Time, A to CLKAB or B to CLKBA	1.5	ns	
t <sub>H</sub>	Hold Time, A to CLKAB or B to CLKBA	2.0	ns	
t <sub>s</sub>	Setup Time, A to LEAB or B to LEBA	1.5	ns	
t <sub>H</sub>	Hold Time, A to LEAB or B to LEBA	2.5	ns	
t <sub>w</sub>	Pulse Width, CLKAB or CLKBA, high or low	2.0	ns	
t <sub>w</sub>	Pulse Width, LEAB or LEBA high	2.0	ns	
f <sub>max</sub>	Maximum CLKAB or CLKBA Clock	250	MHz	
	Frequency			

#### **AC Operating Requirements**

can Test Operation, over recommended operating supply voltage and temperature ranges unless otherwise specified

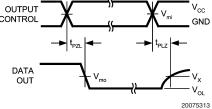
Symbol	Parameter	All Options	Units	
		T <sub>A</sub> = -40°C to +85°C	7	
		C <sub>L</sub> = 30 pF,		
		$R_L = 500\Omega$ to GND		
		Guaranteed Minimum	1	
t <sub>s</sub>	Setup Time, H or L, TMS to TCK	2.0	ns	
t <sub>H</sub>	Hold Time, H or L, TCK to TMS	1.0	ns	
ts	Setup Time, H or L, TDI to TCK	1.0	ns	
t <sub>H</sub>	Hold Time, H or L, TCK to TDI	2.0	ns	
t <sub>w</sub>	Pulse Width TCK High or Low	10	ns	
t <sub>w</sub>	Pulse Width TRST, Low	2.5	ns	
f <sub>max</sub>	Maximum TCK Clock Frequency	25	MHz	
t <sub>REC</sub>	Recovery Time, TRST to TCK	2.0	ns	

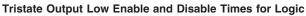


 $V_{cc}$ 

GND

20075311





20075312 Propagation Delay, Pulse Width and  $t_{REC}$  Waveforms

CLOCK

OUTPUT

**AC Loading and Waveforms** 

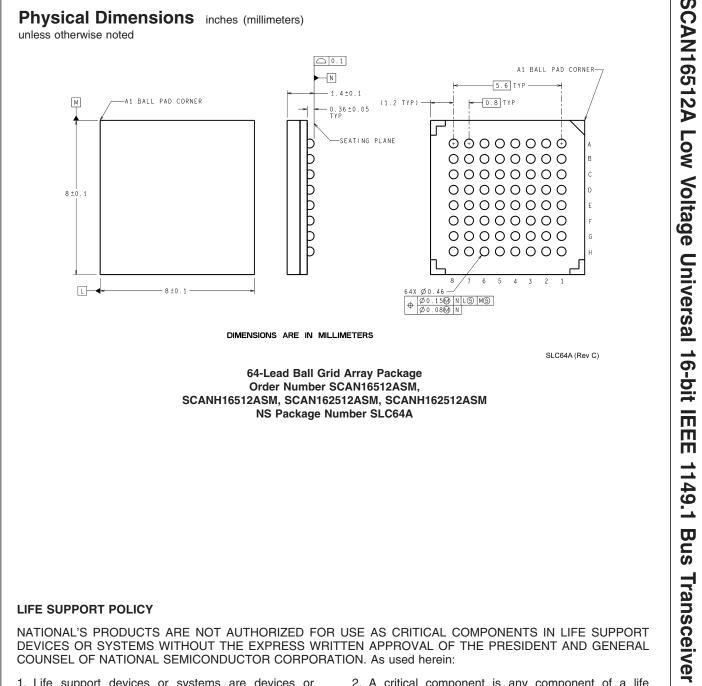
FIGURE 2. Timing Waveforms (Input Characteristics; f = 1MHz,  $t_r = t_f = 2.5$ ns)

Symbol	V <sub>cc</sub> 2.7 - 3.6V	
V <sub>mi</sub>	1.5V	
V <sub>mo</sub>	1.5V	
V <sub>x</sub>	V <sub>OL</sub> + 0.3V	
Vy	V <sub>OH</sub> - 0.3V	

# Capacitance and I/O Characteristics Refer to National's website for IBIS models at http://www.national.com/scan

#### **Device ID Register**

Ordering Code	Features	Device ID	Manufacturer & LSB
SCAN16512ASM	No bus hold, no series resistor	FC30	01F
SCANH16512ASM	With bus hold only	FC31	01F
SCAN162512ASM	With 25 $\Omega$ series resistors in outputs	FC32	01F
SCANH162512ASM	With 25 $\Omega$ series resistors and bus hold	FC33	01F



- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

#### **BANNED SUBSTANCE COMPLIANCE**

National Semiconductor certifies that the products and packing materials meet the provisions of the Customer Products Stewardship Specification (CSP-9-111C2) and the Banned Substances and Materials of Interest Specification (CSP-9-111S2) and contain no "Banned Substances" as defined in CSP-9-111S2.



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